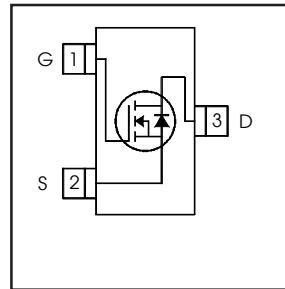


- Generation V Technology
- Ultra Low On-Resistance
- N-Channel MOSFET
- SOT-23 Footprint
- Low Profile (<1.1mm)
- Available in Tape and Reel
- Fast Switching
- Lead-Free
- RoHS Compliant, Halogen-Free

### HEXFET® Power MOSFET



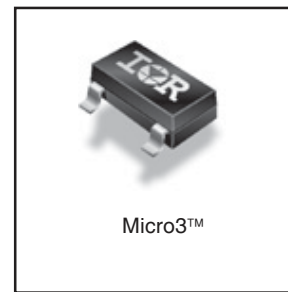
$$V_{DS} = 20V$$

$$R_{DS(on)} = 0.25\Omega$$

### Description

Fifth Generation HEXFETs from International Rectifier utilize advanced processing techniques to achieve extremely low on-resistance per silicon area. This benefit, combined with the fast switching speed and ruggedized device design that HEXFET Power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in a wide variety of applications.

A customized leadframe has been incorporated into the standard SOT-23 package to produce a HEXFET Power MOSFET with the industry's smallest footprint. This package, dubbed the Micro3, is ideal for applications where printed circuit board space is at a premium. The low profile (<1.1mm) of the Micro3 allows it to fit easily into extremely thin application environments such as portable electronics and PCMCIA cards.



| Base Part Number | Package Type     | Standard Pack |          | Orderable Part Number |
|------------------|------------------|---------------|----------|-----------------------|
|                  |                  | Form          | Quantity |                       |
| IRLML2402TRPbF   | Micro3™ (SOT-23) | Tape and Reel | 3000     | IRLML2402TRPbF        |

### Absolute Maximum Ratings

|                          | Parameter                                 | Max.         | Units |
|--------------------------|-------------------------------------------|--------------|-------|
| $I_D @ T_A = 25^\circ C$ | Continuous Drain Current, $V_{GS} @ 4.5V$ | 1.2          | A     |
| $I_D @ T_A = 70^\circ C$ | Continuous Drain Current, $V_{GS} @ 4.5V$ | 0.95         |       |
| $I_{DM}$                 | Pulsed Drain Current ①                    | 7.4          |       |
| $P_D @ T_A = 25^\circ C$ | Power Dissipation                         | 540          | mW    |
|                          | Linear Derating Factor                    | 4.3          | mW/°C |
| $V_{GS}$                 | Gate-to-Source Voltage                    | $\pm 12$     | V     |
| $dv/dt$                  | Peak Diode Recovery $dv/dt$ ②             | 5.0          | V/ns  |
| $T_J, T_{STG}$           | Junction and Storage Temperature Range    | -55 to + 150 | °C    |

### Thermal Resistance

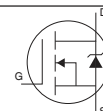
|                 | Parameter                     | Typ. | Max. | Units |
|-----------------|-------------------------------|------|------|-------|
| $R_{\theta JA}$ | Maximum Junction-to-Ambient ④ | —    | 230  | °C/W  |

**Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)**

|                                        | Parameter                            | Min. | Typ.  | Max. | Units | Conditions                                                          |
|----------------------------------------|--------------------------------------|------|-------|------|-------|---------------------------------------------------------------------|
| V <sub>(BR)DSS</sub>                   | Drain-to-Source Breakdown Voltage    | 20   | —     | —    | V     | V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA                        |
| ΔV <sub>(BR)DSS</sub> /ΔT <sub>J</sub> | Breakdown Voltage Temp. Coefficient  | —    | 0.024 | —    | V/°C  | Reference to 25°C, I <sub>D</sub> = 1mA                             |
| R <sub>DS(on)</sub>                    | Static Drain-to-Source On-Resistance | —    | —     | 0.25 | Ω     | V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 0.93A ③                    |
|                                        |                                      | —    | —     | 0.35 |       | V <sub>GS</sub> = 2.7V, I <sub>D</sub> = 0.47A ③                    |
| V <sub>GS(th)</sub>                    | Gate Threshold Voltage               | 0.70 | —     | —    | V     | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA          |
| g <sub>fs</sub>                        | Forward Transconductance             | 1.3  | —     | —    | S     | V <sub>DS</sub> = 10V, I <sub>D</sub> = 0.47A                       |
| I <sub>DSS</sub>                       | Drain-to-Source Leakage Current      | —    | —     | 1.0  | μA    | V <sub>DS</sub> = 16V, V <sub>GS</sub> = 0V                         |
|                                        |                                      | —    | —     | 25   |       | V <sub>DS</sub> = 16V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 125°C |
| I <sub>GSS</sub>                       | Gate-to-Source Forward Leakage       | —    | —     | -100 | nA    | V <sub>GS</sub> = -12V                                              |
|                                        | Gate-to-Source Reverse Leakage       | —    | —     | 100  |       | V <sub>GS</sub> = 12V                                               |
| Q <sub>g</sub>                         | Total Gate Charge                    | —    | 2.6   | 3.9  | nC    | I <sub>D</sub> = 0.93A                                              |
| Q <sub>gs</sub>                        | Gate-to-Source Charge                | —    | 0.41  | 0.62 |       | V <sub>DS</sub> = 16V                                               |
| Q <sub>gd</sub>                        | Gate-to-Drain ("Miller") Charge      | —    | 1.1   | 1.7  |       | V <sub>GS</sub> = 4.5V, See Fig. 6 and 9 ③                          |
| t <sub>d(on)</sub>                     | Turn-On Delay Time                   | —    | 2.5   | —    | ns    | V <sub>DD</sub> = 10V                                               |
| t <sub>r</sub>                         | Rise Time                            | —    | 9.5   | —    |       | I <sub>D</sub> = 0.93A                                              |
| t <sub>d(off)</sub>                    | Turn-Off Delay Time                  | —    | 9.7   | —    |       | R <sub>G</sub> = 6.2Ω                                               |
| t <sub>f</sub>                         | Fall Time                            | —    | 4.8   | —    |       | R <sub>D</sub> = 11Ω, See Fig. 10 ③                                 |
| C <sub>iss</sub>                       | Input Capacitance                    | —    | 110   | —    | pF    | V <sub>GS</sub> = 0V                                                |
| C <sub>oss</sub>                       | Output Capacitance                   | —    | 51    | —    |       | V <sub>DS</sub> = 15V                                               |
| C <sub>rss</sub>                       | Reverse Transfer Capacitance         | —    | 25    | —    |       | f = 1.0MHz, See Fig. 5                                              |

**Source-Drain Ratings and Characteristics**

|                 | Parameter                              | Min. | Typ. | Max. | Units | Conditions                                                            |
|-----------------|----------------------------------------|------|------|------|-------|-----------------------------------------------------------------------|
| I <sub>S</sub>  | Continuous Source Current (Body Diode) | —    | —    | 0.54 | A     | MOSFET symbol showing the integral reverse p-n junction diode.        |
| I <sub>SM</sub> | Pulsed Source Current (Body Diode) ①   | —    | —    | 7.4  |       |                                                                       |
| V <sub>SD</sub> | Diode Forward Voltage                  | —    | —    | 1.2  | V     | T <sub>J</sub> = 25°C, I <sub>S</sub> = 0.93A, V <sub>GS</sub> = 0V ③ |
| t <sub>rr</sub> | Reverse Recovery Time                  | —    | 25   | 38   | ns    | T <sub>J</sub> = 25°C, I <sub>F</sub> = 0.93A                         |
| Q <sub>rr</sub> | Reverse Recovery Charge                | —    | 16   | 24   | nC    | di/dt = 100A/μs ③                                                     |

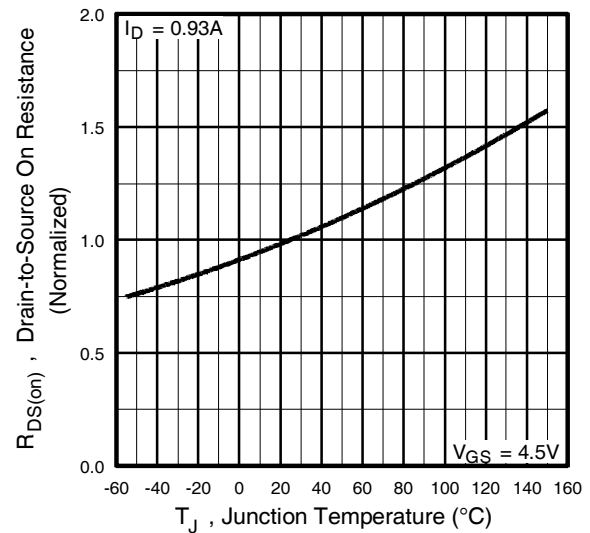
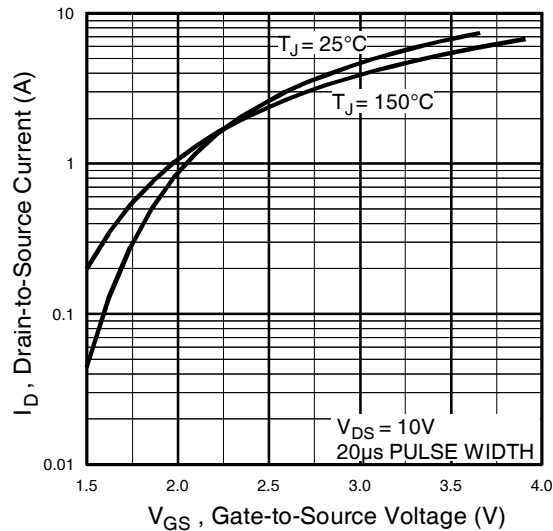
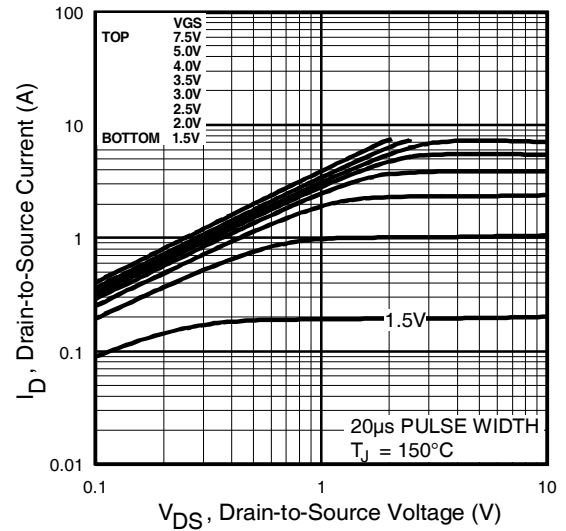
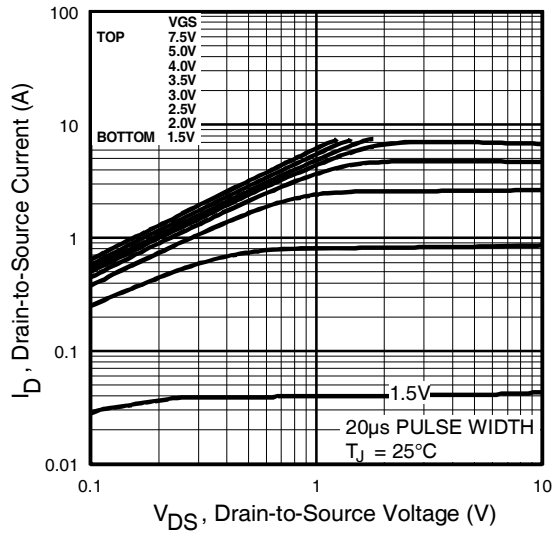

**Notes:**

① Repetitive rating; pulse width limited by max. junction temperature. ( See fig. 11 )

③ Pulse width ≤ 300μs; duty cycle ≤ 2%.

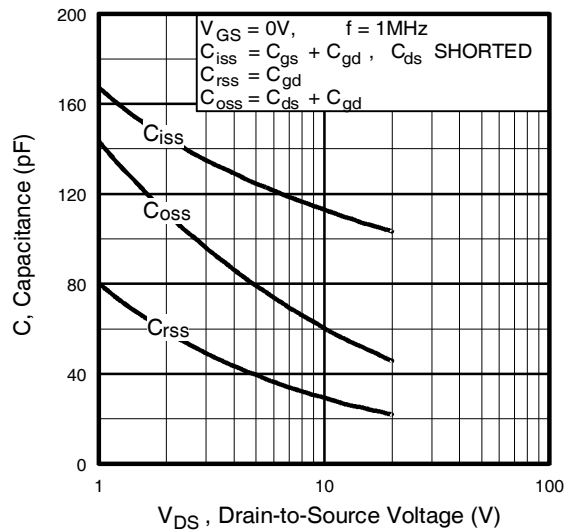
② I<sub>SD</sub> ≤ 0.93A, di/dt ≤ 90A/μs, V<sub>DD</sub> ≤ V<sub>(BR)DSS</sub>, T<sub>J</sub> ≤ 150°C

④ Surface mounted on FR-4 board, t ≤ 5sec.

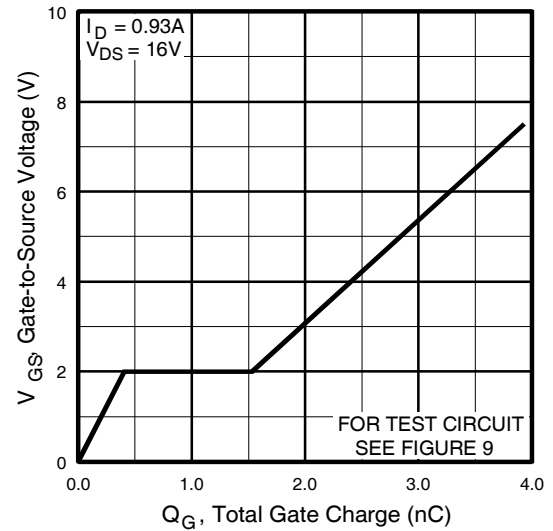


**Fig 3. Typical Transfer Characteristics**

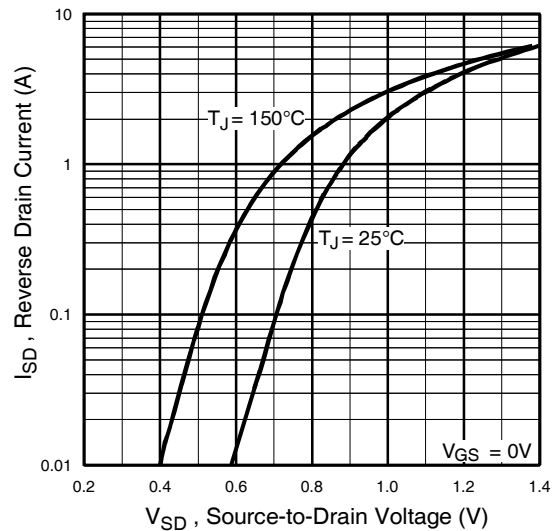
**Fig 4. Normalized On-Resistance Vs. Temperature**



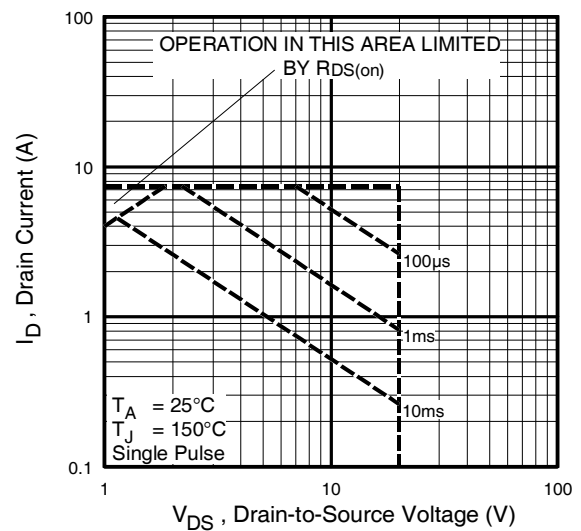
**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



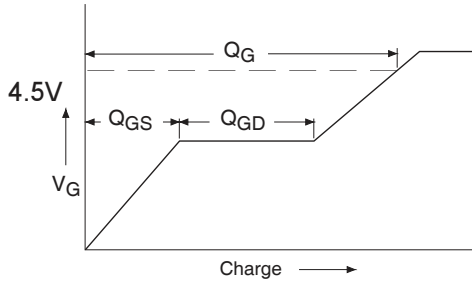
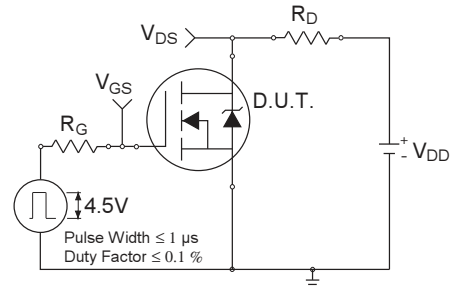
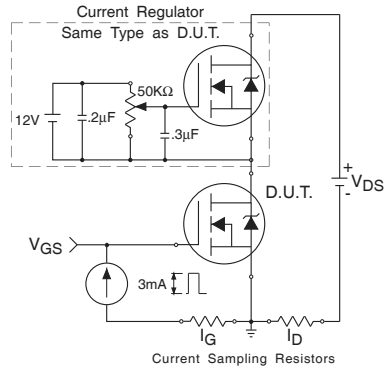
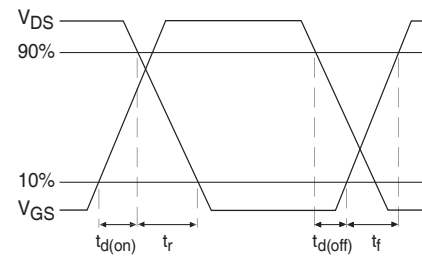
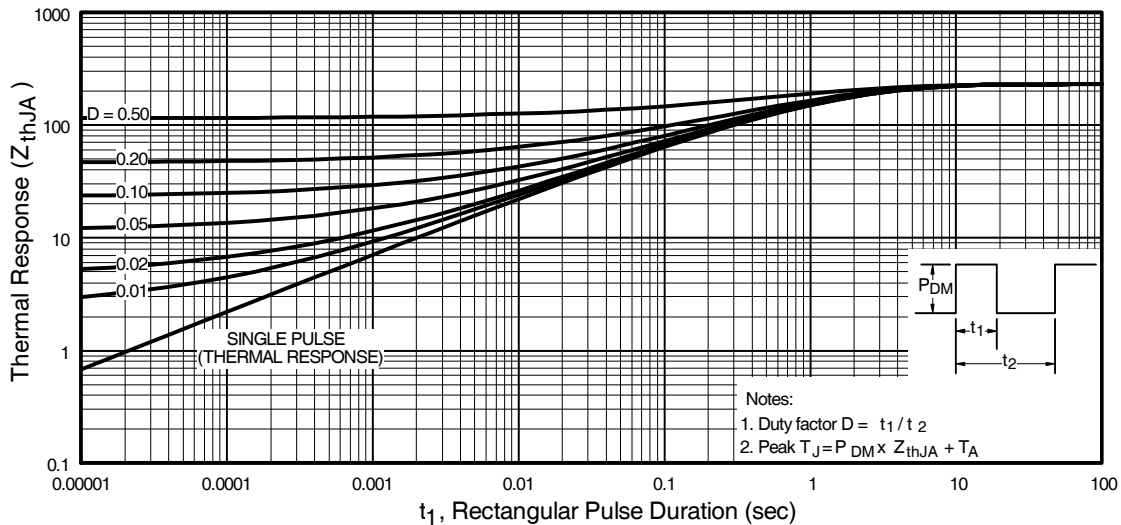
**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



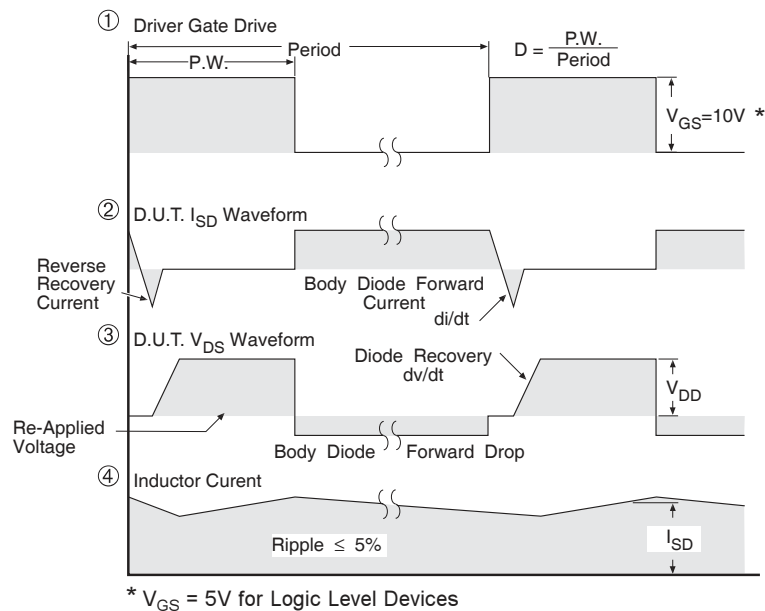
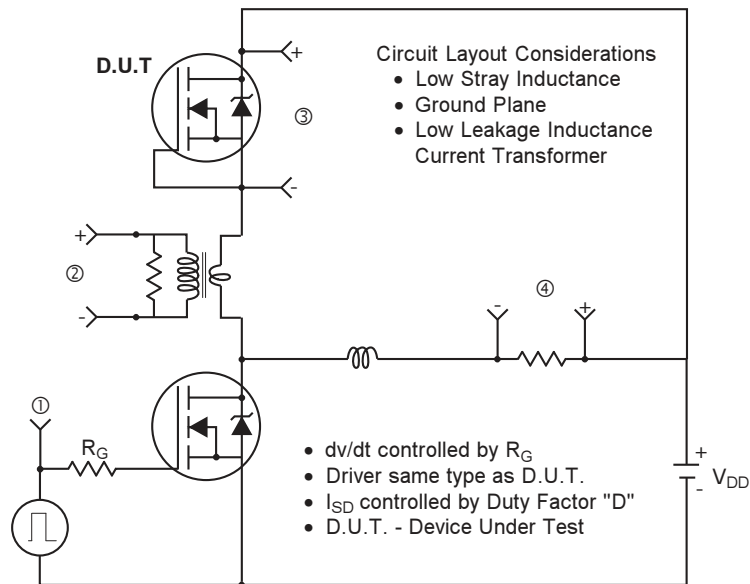
**Fig 7.** Typical Source-Drain Diode Forward Voltage



**Fig 8.** Maximum Safe Operating Area


**Fig 9a. Basic Gate Charge Waveform**

**Fig 10a. Switching Time Test Circuit**

**Fig 9b. Gate Charge Test Circuit**

**Fig 10b. Switching Time Waveforms**

**Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient**

# Peak Diode Recovery dv/dt Test Circuit



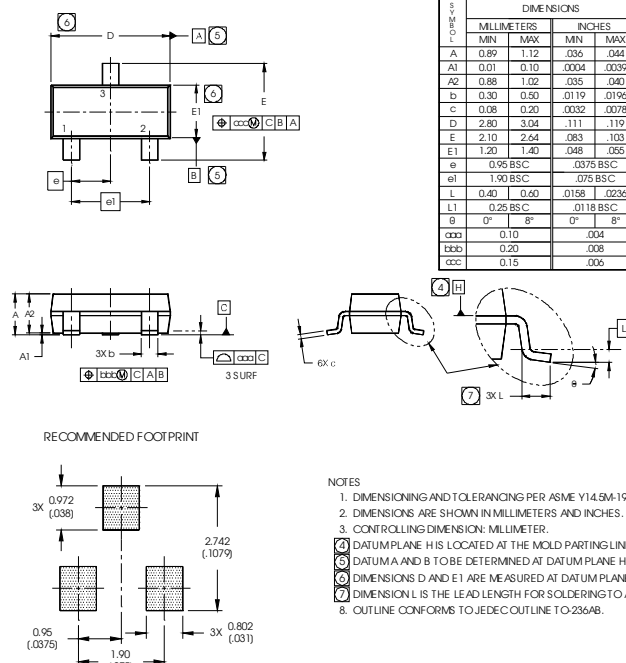
**Fig 12. For N-Channel HEXFETS**



IRLML2402PbF

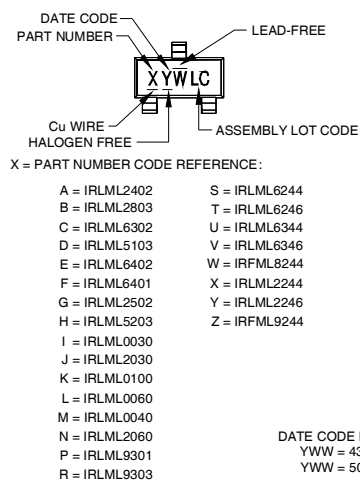
## Micro3 (SOT-23) (Lead-Free) Package Outline

Dimensions are shown in millimeters (inches)



## Micro3 (SOT-23 / TO-236AB) Part Marking Information

Notes: This part marking information applies to devices produced after 02/26/2001



W = (1-26) IF PRECEDED BY LAST DIGIT OF CALENDAR YEAR

| YEAR | Y    | WORK WEEK | W |
|------|------|-----------|---|
| 2011 | 2001 | 01        | A |
| 2012 | 2002 | 02        | B |
| 2013 | 2003 | 03        | C |
| 2014 | 2004 | 04        | D |
| 2015 | 2005 | 05        |   |
| 2016 | 2006 | 06        |   |
| 2017 | 2007 | 07        |   |
| 2018 | 2008 | 08        |   |
| 2019 | 2009 | 09        |   |
| 2020 | 2010 | 24        | X |
|      |      | 25        | Y |
|      |      | 26        | Z |

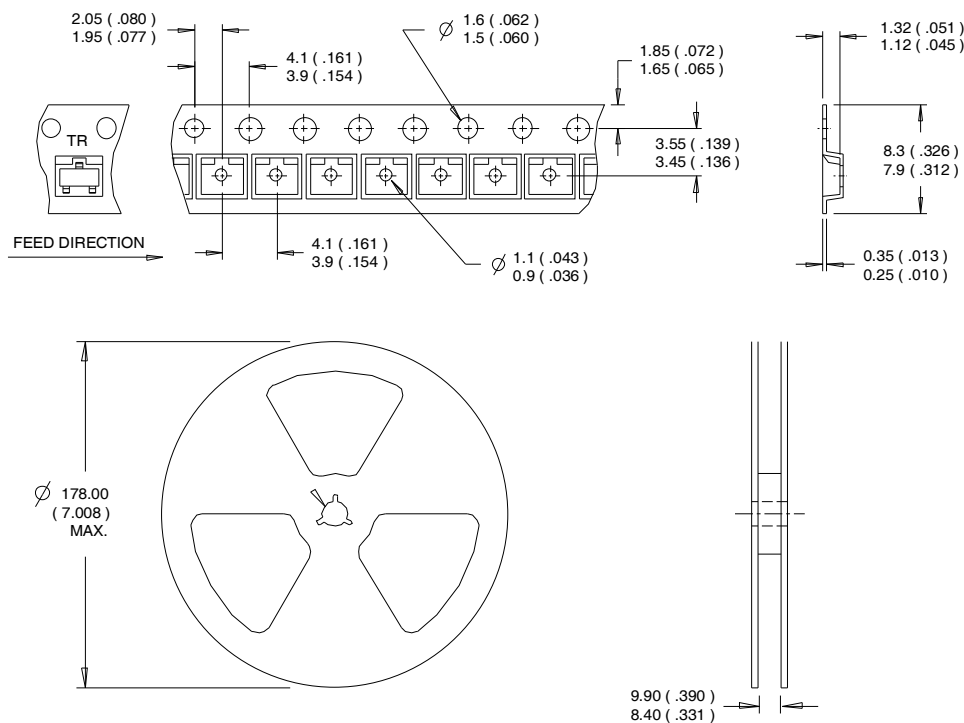
W = (27-52) IF PRECEDED BY A LETTER

| YEAR | Y    | WORK WEEK | W |
|------|------|-----------|---|
| 2011 | 2001 | A 27      | A |
| 2012 | 2002 | B 28      | B |
| 2013 | 2003 | C 29      | C |
| 2014 | 2004 | D 30      | D |
| 2015 | 2005 | E         |   |
| 2016 | 2006 | F         |   |
| 2017 | 2007 | G         |   |
| 2018 | 2008 | H         |   |
| 2019 | 2009 | J         |   |
| 2020 | 2010 | K 50      | X |
|      |      | 51        | Y |
|      |      | 52        | Z |

Note: For the most current drawing please refer to IR website at <http://www.irf.com/package>

## Micro3™ Tape & Reel Information

Dimensions are shown in millimeters (inches)



- NOTES:
1. CONTROLLING DIMENSION : MILLIMETER.
  2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

Note: For the most current drawing please refer to IR website at <http://www.irf.com/package>

**Qualification information<sup>†</sup>**

|                            |                                                          |                                               |
|----------------------------|----------------------------------------------------------|-----------------------------------------------|
| Qualification level        | Consumer<br>(per JEDEC JESD47F <sup>††</sup> guidelines) |                                               |
| Moisture Sensitivity Level | Micro3™ (SOT-23)                                         | MSL1<br>(per JEDEC J-STD-020D <sup>††</sup> ) |
| RoHS compliant             | Yes                                                      |                                               |

<sup>†</sup> Qualification standards can be found at International Rectifier's web site: <http://www.irf.com/product-info/reliability>

<sup>††</sup> Applicable version of JEDEC standard at the time of product release

**Revision History**

| Date      | Comment                                                                                                                                                                                                                                                                                                                                 |
|-----------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 4/24/2014 | <ul style="list-style-type: none"> <li>• Updated data sheet with new IR corporate template.</li> <li>• Updated package outline &amp; part marking on page 7.</li> <li>• Added Qualification table -Qual level "Consumer" on page 9.</li> <li>• Added bullet point in the Benefits "RoHS Compliant, Halogen -Free" on page 1.</li> </ul> |

International  
 Rectifier

**IR WORLD HEADQUARTERS:** 101 N. Sepulveda Blvd., El Segundo, California 90245, USA  
 To contact International Rectifier, please visit <http://www.irf.com/whoto-call/>

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